

MODEL: HSS-B20-085H | **DESCRIPTION:** HEAT SINK**FEATURES**

- TO-220 package
- round hole for component attachment
- solder pin for secure PCB mounting
- black anodized finish

**MODEL**

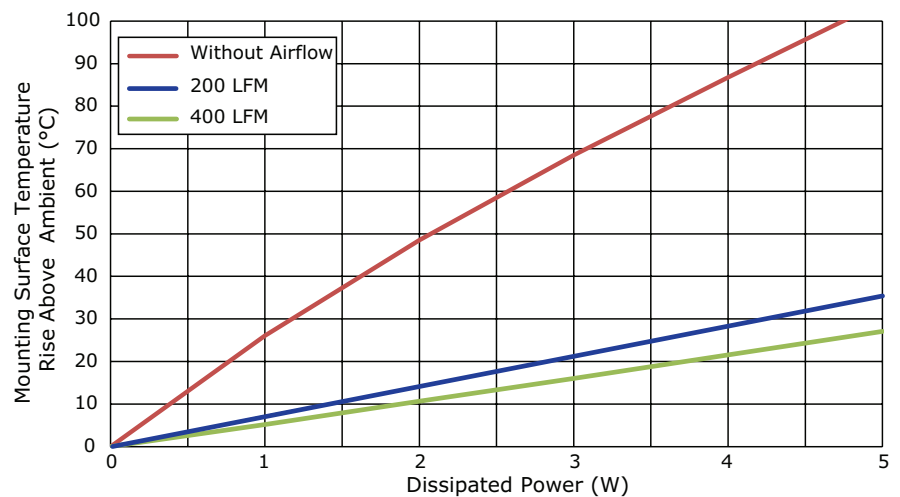
	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS-B20-085H	22.06	26.05	7.46	5.20	3.40

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) (°C)		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	26.05	7.46	5.20
2	48.51	14.24	10.69
3	68.48	21.48	16.04
4	86.75	28.25	21.52
5	104.54	35.39	27.11

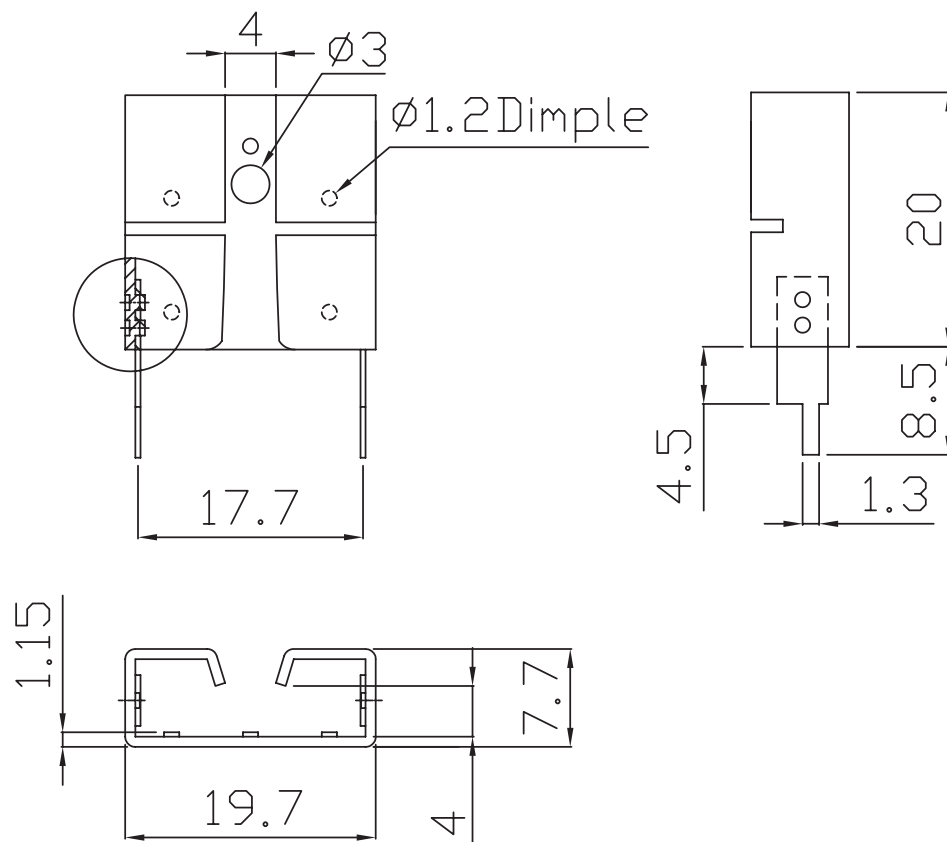
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ± 0.5 mm

MATERIAL	AL5052
FINISH	black anodized
THICKNESS	0.8 mm
PIN MATERIAL	brass
PIN PLATING	tin
WEIGHT	2.0 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/30/2017
1.01	brand update	02/13/2020

The revision history provided is for informational purposes only and is believed to be accurate.

CUI DEVICES

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